

Application No.: 10/810,436

Docket No.: JCLA12013

In The Claims:

Please amend the claims as follows:

1. (original) A chip package, comprising:

a chip, having an active surface and a plurality of bond pads, said bond pads being on said active surface; and

a rigid cover, on said active surface, said rigid cover exposing said plurality of bond pads above said active surface.
2. (withdrawn) The chip package of claim 1, wherein said chip includes a redistribution layer on said active surface to form said plurality of bond pads.
3. (original) The chip package of claim 1, wherein said rigid cover is adhered to said active surface.
4. (original) The chip package of claim 1, wherein said rigid cover having a periphery adhered to said active surface.
5. (original) The chip package of claim 1, wherein the material of said rigid cover includes a conducting material, an insulating material, or a transparent material.
6. (original) The chip package of claim 1, further comprising a plurality of contacts on said plurality of bond pads respectively, the heights of said contacts relative to said active surface are larger than the height of said rigid cover relative to said active surface.

Application No.: 10/810,436

Docket No.: JCLA12013

7. (original) The chip package of claim 1, wherein said plurality of bond pads is disposed on the circumference of said active surface.

8. (original) The chip package of claim 7, wherein said active surface is a rectangle, and said plurality of bond pads are disposed on one side outside of said rectangle.

9. (withdrawn) The chip package of claim 7, wherein said chip has a backside relative to said active surface and a plurality of connecting lines, each of said plurality of connecting lines having an end connected to one of said plurality of bond pads, said plurality of connecting lines extending to said backside via a lateral side of said chip and forming a plurality of terminal pads on said backside respectively.

10. (withdrawn) The chip package of claim 9, wherein said plurality of terminal pads is disposed on the circumference of said backside.

11. (withdrawn) The chip package of claim 9, wherein said plurality of terminal pads is disposed on said backside of said chip as an area array.

12. (withdrawn) The chip package of claim 9, wherein said lateral side of said chip includes a concave surface and portions of said connecting lines are on said concave surface respectively.

Application No.: 10/810,436

Docket No.: JCLA12013

13. (withdrawn) The chip package of claim 9, further comprising a plurality of contacts on said terminal pads respectively.

14. (withdrawn) The chip package of claim 1, wherein said plurality of bond pads are disposed on said active surface as an area array, said rigid cover having a plurality of openings to expose said bond pads respectively.

Claims 15-23 (cancelled)